EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("6350664").PN.	USPAT; USOCR	OR	OFF	2008/06/22 14:48
L2	1	("6710454").PN.	USPAT; USOCR	OR	OFF	2008/06/22 15:13
L3	679	(@ad<"20000216") and ((wafer and (hole$1 or via$1 or trench$2)) with (encapsulant or encapsulation or epoxy or resin or thermo$2plastic or elastomer$2 or compliant))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:18
L4	1080	(@ad<"20000216") and ((wafer and (groove$1 or cavit$3 or hole$1 or via$1 or trench$2)) with (encapsulant or encapsulation or epoxy or resin or thermo$2plastic or elastomer$2 or compliant))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:19
L5	110	L4 and ((groove$1 or cavit $3 or hole$1 or via$1 or trench$2) with (laser or yag or excimer or carbon $2dioxide))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:21
L6	11	L5 and ((align or alignment) with (laser or yag or excimer or carbon$2dioxide))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:22
L7	5	L4 and ((align$2ment near (mark$1 or keys$1 or datum)) same (laser or yag or excimer or carbon $2dioxide))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:28
L8	5	L4 and ((align$2ment near (mark$1 or keys$1 or datum $1)) same (laser or yag or excimer or carbon $2dioxide))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:28

L9	1918	wafer and ((align$2ment near (mark$1 or keys$1 or datum$1)) same (laser or yag or excimer or carbon $2dioxide))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:31
L10	1208	wafer and ((align$2ment near (mark$1 or keys$1 or datum$1)) with (laser or yag or excimer or carbon $2dioxide))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:32
L11	3	LI0 and ((groove$1 or cavit $3 or hole$1 or via$1 or trench$2) with (laser or yag or excimer or carbon $2dioxide))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:32
L12	1918	wafer and ((align$2ment near (mark$1 or keys$1 or datum$1)) same (laser or yag or excimer or carbon $2dioxide))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:34
L13	3823	wafer and ((align or align $2ment near (mark$1 or keys$1 or datum$1)) same (laser or yag or excimer or carbon$2dioxide))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:34
L14	10	LI3 and ((groove$1 or cavit $3 or hole$1 or via$1 or trench$2) with (laser or yag or excimer or carbon $2dioxide))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:34
L15	88	I3 and ((hole$1 or via$1 or trench$2) with (align$3 or alignment))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:37
L16	40	LI5 and (laser or yag or excimer or carbon$2dioxide)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 15:37

L17	12111	(@ad< "20000216") and (((chip or die or wafer) and (groove$1 or etch$3 or hole $1 or via$1 or trench$2)) with (encapsulant or encapsulation or epoxy or resin or thermo$2plastic or elastomer$2 or compliant))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 16:25
L18	0	LI7 and ((laser or yag or excimer or carbon$2dioxide) with (ablat$3 or etch$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 16:28
L19	72477	(@ad< "20000216") and ((chip or die or wafer) with (encapsulant or encapsulation or epoxy or resin or thermo$2plastic or elastomer$2 or compliant))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 16:29
L20	0	LI9 and ((laser or yag or excimer or carbon$2dioxide) with (ablat$3 or etch$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 16:32
L21	70324	((laser or yag or excimer or carbon$2dioxide) with (ablat $3 or etch$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 16:32
L22	875	I19 and I21	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 16:33
L23	109	L22 and ((laser or yag or excimer or carbon$2dioxide) with reflect$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 16:34
L24	68	L22 and ((alignment or align or mark or key$1 or position $3) with reflect$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 16:36

L25	110	(@ad< "20000216") and ((wafer and (hole$1 or via$1 or trench$2)) with (thermo $2plastic or elastomer$2 or compliant))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 16:47
L26	1	("6399178").PN.	USPAT; USOCR	OR	OFF	2008/06/22 16:48
L27	146	(@ad< "20000216") and ((wafer and (hole$1 or via$1 or trench$2 or groove$1)) with (thermo$2plastic or elastomer$2 or compliant))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 17:01
L28	3	"09045726"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 17:23
L29	7	L3 and (thermo$2plastic near elastomer$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 18:03
L30	0	wader$2scale and (thermo $2plastic with elastomer$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 18:06
L31	10	wafer$2scale and (thermo $2plastic with elastomer$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 18:06
L32	2	l31 and (@ad< "20000216")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 18:08
L33	17	wafer$2scale and (wafer with elastomer$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 18:11

L34	7	l33 and (@ad<"20000216")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 18:12
L35	6	L34 and stress	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 18:13
L36	1124	(wafer with elastomer$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 18:21
L37	120	l36 and (@ad<"20000216") and stress	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 18:21
L38	58	(wafer and stress) with elastomer$2	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 18:24
L39	13	l38 and (@ad<"20000216")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 18:26
L40	11	L38 and ((spinor spinning or liquid) with elastomer$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 18:31
L41	2	l40 and (@ad<"20000216")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 18:31
L42	1	("5747101").PN.	USPAT; USOCR	OR	OFF	2008/06/22 18:52

L43	65	(@ad< "20000216") and 257/778.ccls. and underfill $3 and ((protect$3 with encapsulant or encapsulation))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 19:36
L44	28	(@ad< "20000216") and 257/778.ccls. and underfill $3 and (protect$3 with (encapsulant or encapsulation))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/22 19:40
L45	1	("5808874").PN.	USPAT; USOCR	OR	OFF	2008/06/22 19:58
L46	1	("5747101").PN.	USPAT; USOCR	OR	OFF	2008/06/22 20:53

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